





PROGRAM SCHEDULE



PENANG, MALAYSIA JULY 24 & 25, 2024

July 24, 2024 Venue: Setia Spice Convention Centre, Penang Day - 1	
Time	Program
9:30 AM - 5:00 PM	Hand Soldering Rework Competition @ IPC Pavilion at EMAX Expo
10:00 AM – 4:30 PM	B2B Meetings between Malaysian & International Delegates
July 25, 2024 Venue: Hotel Olive Tree, Penang Day - 2	
9:30 AM - 5:00 PM	Hand Soldering Competition @IPC Pavilion at EMAX Expo/Setia SPICE Convention Centre
10:00 - 11:30 AM	Introduction: David Bergman, IPC Vice President Standards & Technology Welcome Address: MATRADE Keynote: Dr John W Mitchell, President & CEO - IPC Topic: Success of electronics industry depends on the Skilled Workforce Address by Chief Guest: HE Mr Jagdeep Singh Deo, Deputy Chief Minister Penang, Malaysia Vote of Thanks: David Bergman, IPC Vice President Standards & Technology
11:30 - 1:00 PM	Special Session: Advanced Packaging of Semiconductors Presentation: Advanced Packaging of Semiconductors: The need to Build an Industrial Eco System: David Bergman - Vice President (Standards & Technology IPC & Session Moderator Presentation: Advanced packaging: Frontier of semiconductor technology Speaker: Intel, USA (TBC) Presentation: Need for global participation in Advanced packaging of semiconductors Speaker: Japanese Semiconductor Packaging Consortium (TBC) Q & A session
1:00 – 2:00 PM	Networking Lunch
2:00 - 3:30 PM	Panel Discussion: Importance of Advanced Packaging Technology @Semiconductor & Electronics Industry Session Moderator: Bernard Lim - Vice President, Director and co-founder of Appscard Group Panel Members Invited: TBC Malaysia Semiconductor Industry Association (MSIA) Ang Wee Seng, Executive Director - SSIA Dr. Veerappan V, Chairperson - IESA Semiconductor and Electronics Industries in the Philippines (SEIPI) Taiwan Semiconductor Industry Association (TSIA) Vietnam Electronics Industries Association (VEIA)
3:30 - 5:00 PM	Guided tour to EMAX show